L Number	Hits	Search Text	DB	Time stamp
11	4	6429506.URPN.	USPAT	2004/09/02 17:41
12	2	6245593.pn.	USPAT; US-PGPUB;	17:41   2004/09/02   17:51
13	7	("4921564"   "5435876"   "5597767"   "5759874"   "5824177"   "5843251"   "5976691").PN.	EPO; JPO; DERWENT USPAT	2004/09/02 17:45
14	5	6245593.URPN.	USPAT	2004/09/02
16	0	((cap with cavity) and (mem or (micro adj electromechanical)) and (@ad<20001205 or @rlad<20001205)) and (transfer adj tape) and (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/02 17:53
17	0		USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/02
15	110	(cap with cavity) and (mem or (micro adj electromechanical)) and (@ad<20001205 or @rlad<20001205)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/02
-	6	same (etched adj ports)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/02 14:46
-	6	(dicing adj tape) with (through adj hole) with backside	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:10
-	13	("4791075"   "4907065"   "5150196"   "5323051"   "5362681"   "5435876"   "5610431"   "5824177"   "5831162"   "6106735"   "6109113"   "6210514"   "6410360").PN.	USPAT	2003/11/12 18:09
-	6	·	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:11
-	12	(dicing adj tape) and ((hole or via or open\$3 or interconnect) with (substrate or wafer)) and (transfer adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12
_	194	open\$3 or interconnect) with (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12
_	53	<pre>open\$3 or interconnect) with (substrate or wafer))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12
_	20	<pre>((dicing adj tape) same ((hole or via or open\$3 or interconnect) with (substrate or wafer))) and @ad&lt;20001205</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12
-	26	(dicing adj tape) with wafer with backside	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:58
_	148	tape with wafer with backside	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12
-	246	tape with (wafer or substrate) with backside	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:59

-	1713		USPAT;	2003/11/12
		with (wafer or substrate) with backside	US-PGPUB;	19:00
			EPO; JPO;	
_	38	(tape with (wafer or substrate) with	DERWENT USPAT;	2003/11/12
_	38	backside   and ((hole or open\$3 or via or	US-PGPUB;	19:00
		interconnect) with (wafer or substrate)	EPO; JPO;	19.00
		with backside)	DERWENT	
l <u>-</u>	22		USPAT;	2003/11/12
		backside) and ((hole or open\$3 or via or	US-PGPUB;	19:00
		interconnect) with (wafer or substrate)	EPO; JPO;	
		with backside)) and dic\$3	DERWENT	
-	6		USPAT;	2003/11/12
		backside) and ((hole or open\$3 or via or	US-PGPUB;	19:00
		interconnect) with (wafer or substrate)	EPO; JPO; DERWENT	
		with backside)) and dic\$3) and @ad<20001205	DEKWENI	
_	2	5362681.pn.	USPAT;	2003/11/13
	-	3302001.pm.	US-PGPUB;	11:56
			EPO; JPO;	
			DERWENT	
_	56	5362681.URPN.	USPAT	2003/11/13
				11:53
_	6315	((bottom or (back adj side)) with (tape	USPAT;	2003/11/13
		or adhesive)) same (dic\$3 or cut\$4)	US-PGPUB;	11:57
			EPO; JPO;	
_	469	((bottom or (back adj side)) with (tape	DERWENT USPAT;	2003/11/13
_	409	or adhesive) with (wafer or substrate))	US-PGPUB;	11:58
		same (dic\$3 or cut\$4)	EPO; JPO;	11.30
		bane (aloyo of oacy 1)	DERWENT	
-	257327	(wafer or substrate) with (via hole	USPAT;	2003/11/13
		open\$3 interconnect)	US-PGPUB;	11:59
			EPO; JPO;	
			DERWENT	
=	80		USPAT;	2003/11/13
		or adhesive) with (wafer or substrate)) same (dic\$3 or cut\$4)) same ((wafer or	US-PGPUB; EPO; JPO;	14:27
		substrate) with (via hole open\$3	DERWENT	
		interconnect)	DEKWENT	
_	l o	, ,	USPAT;	2003/11/13
		or adhesive) with (wafer or substrate))	US-PGPUB;	11:59
		same (dic\$3 or cut\$4)) same ((wafer or	EPO; JPO;	
		substrate) with (via hole open\$3	DERWENT	
	_	interconnect))) and 5362681.URPN.	TIGD 3 TO	2002/11/12
-	8	5362681.URPN. and (((bottom or (back adj	USPAT;	2003/11/13
		side)) with (tape or adhesive) with (wafer or substrate)) same (dic\$3 or	US-PGPUB; EPO; JPO;	10:29
		cut\$4))	DERWENT	
_	1	007585.apn.	USPAT;	2003/11/13
	_		US-PGPUB;	12:12
			EPO; JPO;	
			DERWENT	
_	43	((((bottom or (back adj side)) with (tape	USPAT;	2003/11/13
		or adhesive) with (wafer or substrate))	US-PGPUB;	12:12
		same (dic\$3 or cut\$4)) same ((wafer or	EPO; JPO;	
		substrate) with (via hole open\$3 interconnect))) and @ad<20001205	DERWENT	
_	15	("4872825"   "4933744"   "5178957"	USPAT	2003/11/13
		"5497033"   "5685885"   "5730922"		12:35
		"5747101"   "5761801"   "5766979"		-
		"5848467"   "5866952"   "5958995"		
		"5962608"   "5971253"   "6007407").PN.		
_	344	(((bottom or (back adj side)) with (tape	USPAT;	2003/11/13
		or adhesive) with (wafer or substrate))	US-PGPUB;	14:29
		same (dic\$3 or cut\$4)) and ((wafer or substrate) with (bottom or (back adj	EPO; JPO; DERWENT	
		substrate; with (bottom or (back ad)   side) with etch\$3))	DEKMENI	
L	L	DIGC, MICH CCCHO)!	l	<u> </u>

(((bottom or (back adj side)) with (tape USPAT; 2003/11/13 or adhesive) with (wafer or substrate)) US-PGPUB; 14:29 EPO; JPO; same (dic\$3 or cut\$4)) same ((wafer or substrate) with (bottom or (back adj DERWENT side) with etch\$3)) ((((bottom or (back adj side)) with (tape USPAT; 2003/11/13 or adhesive) with (wafer or substrate)) US-PGPUB; 17:20 same (dic\$3 or cut\$4)) same ((wafer or EPO; JPO; DERWENT substrate) with (bottom or (back adj side) with etch\$3))) and 438/\$3.ccls. (((((bottom or (back adj side)) with USPAT; 2003/11/13 (tape or adhesive) with (wafer or US-PGPUB; 17:31 substrate)) same (dic\$3 or cut\$4)) same EPO; JPO; ((wafer or substrate) with (bottom or DERWENT (back adj side) with etch\$3))) and 438/\$3.ccls.) and @ad<20001205 2003/11/13 8 | uv with tape with needle USPAT: US-PGPUB; 16:31 EPO; JPO; DERWENT (uv with tape) same needle USPAT; 2003/11/13 11 US-PGPUB; 16:33 EPO; JPO; DERWENT (ultraviolet with tape) same needle USPAT: 2003/11/13 US-PGPUB; 16:39 EPO; JPO; DERWENT 72 (ultraviolet with adhesive) same needle USPAT; 2003/11/13 US-PGPUB; 16:40 EPO; JPO; DERWENT ((ultraviolet with adhesive) same needle) USPAT; 2003/11/13 US-PGPUB; 17:03 same dic\$3 EPO; JPO; DERWENT 2003/11/13 7 (transfer adj tape) with (dicing adj USPAT: US-PGPUB; 19:04 EPO; JPO; DERWENT 1389 (transfer adj tape) with (adhesive) USPAT; 2003/11/13 17:30 US-PGPUB: EPO; JPO; DERWENT USPAT; 2003/11/13 ((transfer adj tape) with (adhesive)) US-PGPUB; 17:05 with dicing EPO; JPO; DERWENT ((transfer adj tape) with (adhesive)) USPAT; 2003/11/13 17:05 same dicing US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/11/13 11 (transfer adj tape) with dicing US-PGPUB; 17:06 EPO; JPO; DERWENT 7 2003/11/13 (transfer adj tape) same (dicing adj USPAT; US-PGPUB; 17:28 tape) EPO; JPO; DERWENT 15 ((transfer adj tape) with (adhesive)) and USPAT; 2003/11/13 438/\$3.ccls. US-PGPUB; 17:30 EPO; JPO; DERWENT 2003/11/13 0 (pickup adj tape) same (dicing adj tape) USPAT; US-PGPUB; 17:28 EPO; JPO; DERWENT (pickup adj tape) and (dicing adj tape) USPAT; 2003/11/13 2 US-PGPUB; 17:28 EPO; JPO; DERWENT

Search History 9/2/0

9/2/04 6:18:11 PM

-	236	(dicing adj tape) with (adhesive)	USPAT;	2003/11/13
			US-PGPUB;	17:30
			EPO; JPO;	
	7.0	((dicing adj tape) with (adhesive)) and	DERWENT	2003/11/13
-	/ /	438/\$3.ccls.	USPAT; US-PGPUB;	17:31
		430743.0013.	EPO; JPO;	17.51
			DERWENT	
_	24	(((dicing adj tape) with (adhesive)) and	USPAT;	2003/11/13
		438/\$3.ccls.) and @ad<20001205	US-PGPUB;	17:31
			EPO; JPO;	
			DERWENT	
-	6	(releas\$3 adj tape) with (dicing adj	USPAT;	2003/11/13
		tape)	US-PGPUB;	19:05
			EPO; JPO;	
	1	006066 277	DERWENT USPAT;	2003/11/14
-	1	006966.apn.	US-PGPUB;	11:34
			EPO; JPO;	11.53
			DERWENT	
l <u>-</u>	l 0	((dic\$3 adj tape) same (mem or mems)) and	USPAT;	2004/04/26
		(@ad<20001205 or @rlad<20001205)	US-PGPUB;	15:24
			EPO; JPO;	
			DERWENT	
-	11	(dic\$3 adj tape) same (mem or mems)	USPAT;	2004/04/26
			US-PGPUB;	15:24
			EPO; JPO; DERWENT	
_	12	("4791075"   "4907065"   "5150196"	USPAT	2004/04/26
-	13	"5323051"   "5362681"   "5435876"	USPAI	15:15
		"5610431"   "5824177"   "5831162"		13.13
		"6106735"   "6109113"   "6210514"		
		"6410360").PN.		
-	26	(dic\$3 adj tape) and (mem or mems)	USPAT;	2004/04/26
			US-PGPUB;	15:24
			EPO; JPO;	
		<del>.</del>	DERWENT	2024/04/25
-	11		USPAT;	2004/04/26
Ì		(@ad<20001205 or @rlad<20001205)	US-PGPUB; EPO; JPO;	16:37
			DERWENT	
_	132	438/45\$1.ccls. and (mems or mem)	USPAT;	2004/04/26
	132	100, 1041.0010. 4114 (1101111 01 110111)	US-PGPUB;	16:37
			EPO; JPO;	
	1		DERWENT	
-	75	(438/45\$1.ccls. and (mems or mem)) and	USPAT;	2004/04/26
	1	(@ad<20001205 or @rlad<20001205)	US-PGPUB;	16:37
	1		EPO; JPO;	
	,	((438/45\$1.ccls. and (mems or mem)) and	DERWENT USPAT;	2004/04/26
-	1	((438/45\$1.0018. and (mems or mem)) and ((ead<20001205)) and	US-PGPUB;	16:50
	1	(dic\$3 with tape)	EPO; JPO;	
	1	,	DERWENT	
_	4	((438/45\$1.ccls. and (mems or mem)) and	USPAT;	2004/04/26
	1	(@ad<20001205 or @rlad<20001205)) and	US-PGPUB;	16:50
	1	tape	EPO; JPO;	
		/#540D00D#   #54D4545#   #54D545#	DERWENT	0004/04/05
-	8	("5187007"   "5476566"   "5605489"	USPAT	2004/04/26
	1	"5923995"   "6010782"   "6245593"		17:05
1_	77	"6297131"   "6320266").PN.   (((wafer adj cap) or tape) with cavity)	USPAT;	2004/09/02
-	l ''	and (mem or (micro adj	US-PGPUB;	14:59
		electromechanical))	EPO; JPO;	
	1		DERWENT	
-	2	6429506.pn.	USPAT;	2004/09/02
		_	US-PGPUB;	17:45
			EPO; JPO;	
	_	[ <u>.</u>	DERWENT	
-	50		USPAT;	2004/09/02
İ		and (mem or (micro adj	US-PGPUB;	17:51
	1	electromechanical))) and (@ad<20001205 or @rlad<20001205)	EPO; JPO; DERWENT	
L	L	GTT@U/50001500)	PERMENT	<u> </u>

-	15	("4921564"   "5362681"   "5435876"	USPAT	2004/09/02
l i		"5597767"   "5824177"   "6107685"		15:55
		"6124637"   "6313532"   "6198165"		
		"6201707"   "6204564"   "6208525"		
		"6165885"   "6232650"   "6291895").PN.		